

PIMZ2; PUMZ2

NPN/PNP general-purpose double transistors

Rev. 06 — 17 November 2009

Product data sheet

1. Product profile

1.1 General description

NPN/PNP general-purpose double transistors.

Table 1. Product overview

Type number	Package		Configuration
	NXP	JEITA	
PIMZ2	SOT457	SC-74	NPN/PNP double transistors
PUMZ2	SOT363	SC-88	NPN/PNP double transistors

1.2 Features

- Simplified circuit design
- Reduced component count
- Reduced pick and place costs

1.3 Applications

- General-purpose switching and amplification

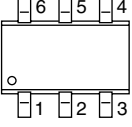
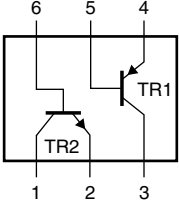
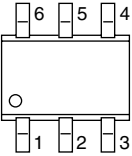
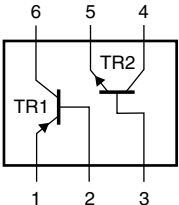
1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CE0}	collector-emitter voltage	open base	-	-	50	V
I_C	collector current (DC)		-	-	150	mA

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
PIMZ2 (SOT457)			
1	collector TR2		 <p style="text-align: right;"><i>sym082</i></p>
2	emitter TR2		
3	collector TR1		
4	emitter TR1		
5	base TR1		
6	base TR2		
PUMZ2 (SOT363)			
1	emitter TR1		 <p style="text-align: right;"><i>sym083</i></p>
2	base TR1		
3	base TR2		
4	collector TR2		
5	emitter TR2		
6	collector TR1		

3. Ordering information

Table 4. Ordering information

Type number	Package		Version
	Name	Description	
PIMZ2	SC-74	plastic surface mounted package; 6 leads	SOT457
PUMZ2	SC-88	plastic surface mounted package; 6 leads	SOT363

4. Marking

Table 5. Marking codes

Type number	Marking code ^[1]
PIMZ2	M6
PUMZ2	GZ*

[1] * = -: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per transistor; for the PNP transistor with negative polarity					
V_{CBO}	collector-base voltage	open emitter	-	60	V
V_{CEO}	collector-emitter voltage	open base	-	50	V
V_{EBO}	emitter-base voltage	open collector	-	7	V
I_C	collector current (DC)		-	150	mA
I_{CM}	peak collector current		-	200	mA
I_{BM}	peak base current		-	100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$			
	SOT457		[1] -	200	mW
	SOT363		[1] -	180	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-	150	°C
T_{amb}	ambient temperature		-65	+150	°C
Per device					
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$			
	SOT457		[1] -	300	mW
	SOT363		[1] -	300	mW

[1] Device mounted on an FR4 printed-circuit board.

6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
$R_{th(j-a)}$	thermal resistance from junction to ambient	$T_{amb} \leq 25\text{ °C}$				
	SOT457		[1] -	-	625	K/W
	SOT363		[1] -	-	694	K/W
Per device						
$R_{th(j-a)}$	thermal resistance from junction to ambient	$T_{amb} \leq 25\text{ °C}$				
	SOT457		[1] -	-	417	K/W
	SOT363		[1] -	-	417	K/W

[1] Device mounted on an FR4 printed-circuit board.

7. Characteristics

Table 8. Characteristics

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor; for the PNP transistor with negative polarity; unless otherwise specified						
I_{CBO}	collector-base cut-off current	$V_{CB} = 60\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
		$V_{CB} = 60\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ °C}$	-	-	50	μA
I_{EBO}	emitter-base cut-off current	$V_{EB} = 7\text{ V}; I_C = 0\text{ A}$	-	-	100	nA
h_{FE}	DC current gain	$V_{CE} = 6\text{ V}; I_C = 1\text{ mA}$	120	250	560	
TR1 (PNP)						
V_{CEsat}	collector-emitter saturation voltage	$I_C = -50\text{ mA}; I_B = -5\text{ mA}$	-	-	-500	mV
f_T	transition frequency	$I_E = -2\text{ mA}; V_{CE} = -12\text{ V}; f = 100\text{ MHz}$	-	190	-	MHz
C_c	collector capacitance	$I_E = i_e = 0\text{ A}; V_{CB} = -12\text{ V}; f = 1\text{ MHz}$	-	2.3	5	pF
TR2 (NPN)						
V_{CEsat}	collector-emitter saturation voltage	$I_C = 50\text{ mA}; I_B = 5\text{ mA}$	-	-	250	mV
f_T	transition frequency	$I_E = 2\text{ mA}; V_{CE} = 12\text{ V}; f = 100\text{ MHz}$	100	-	-	MHz
C_c	collector capacitance	$I_E = i_e = 0\text{ A}; V_{CB} = 12\text{ V}; f = 1\text{ MHz}$	-	-	3	pF

8. Package outline

Plastic surface-mounted package (TSOP6); 6 leads

SOT457

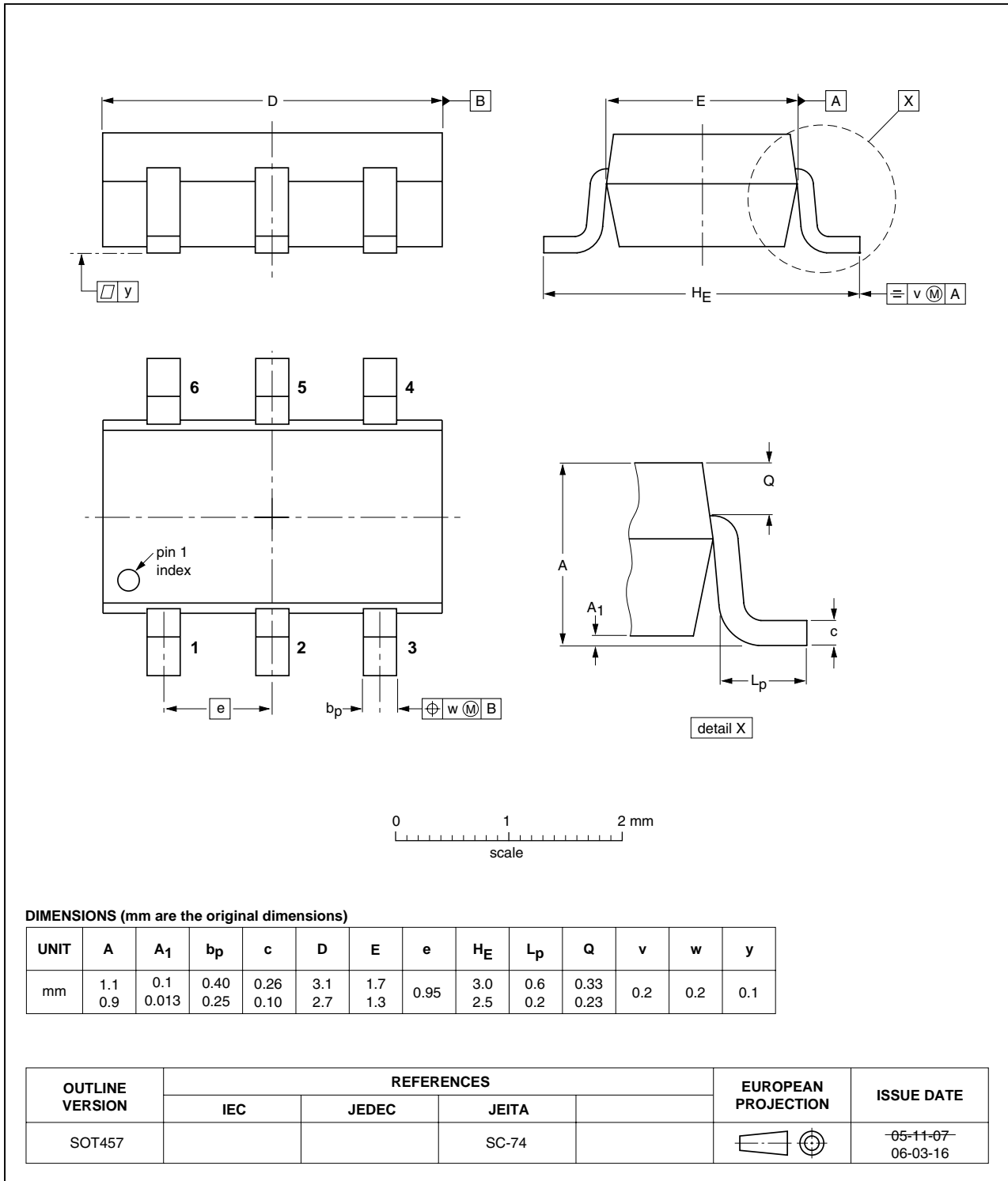


Fig 1. Package outline SOT457 (SC-74)

Plastic surface-mounted package; 6 leads

SOT363

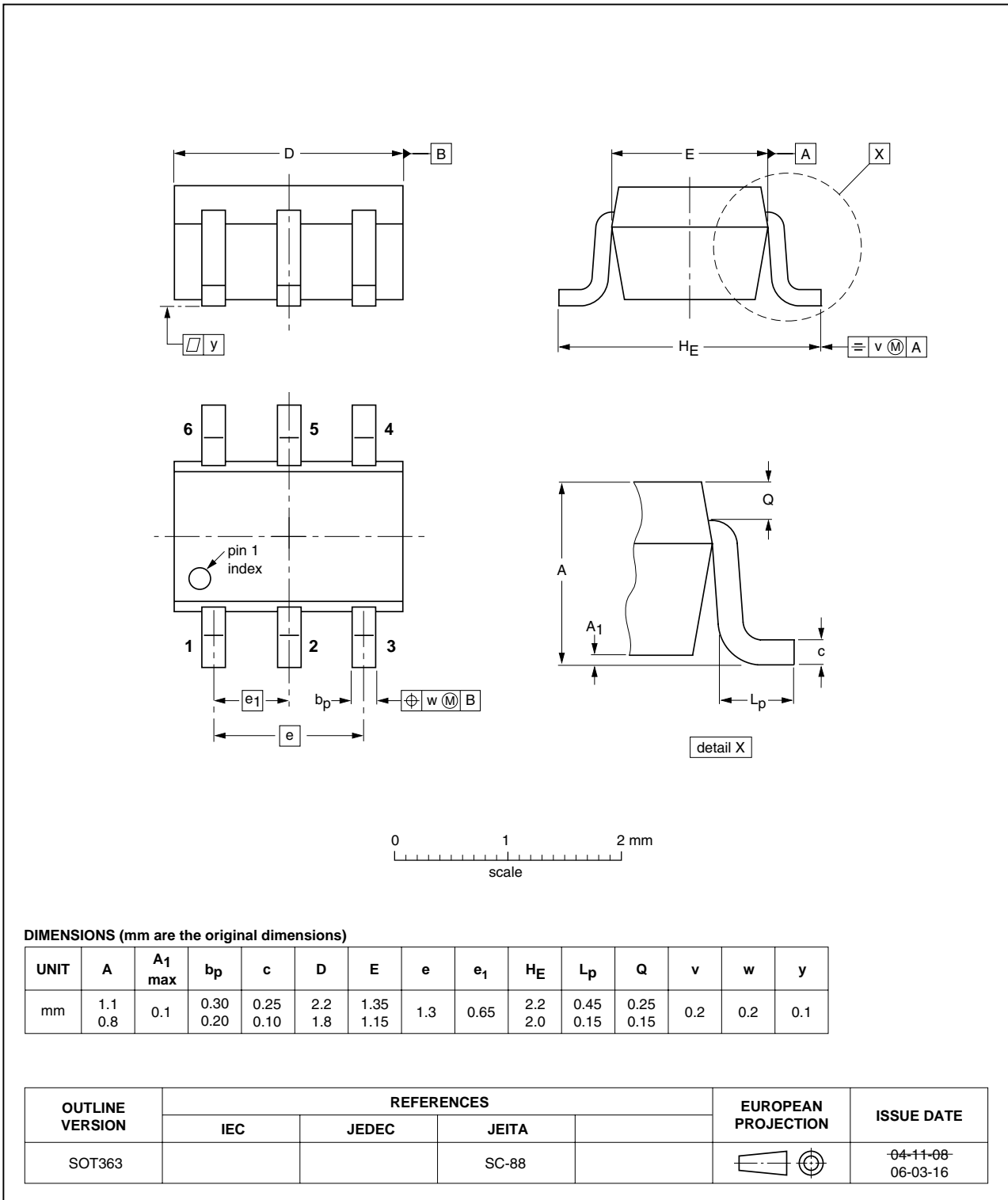


Fig 2. Package outline SOT363 (SC-88)

9. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PIMZ2_PUMZ2_6	20091117	Product data sheet	-	PIMZ2_PUMZ2_5
Modifications:	<ul style="list-style-type: none"> • This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. • Table 3 “Pinning”: updated • Figure 1 “Package outline SOT457 (SC-74)”: updated • Figure 2 “Package outline SOT363 (SC-88)”: updated 			
PIMZ2_PUMZ2_5	20041124	Product data sheet	-	PIMZ2_PUMZ2_4
PIMZ2_PUMZ2_4	20031217	Product specification	-	PIMZ2_2
PIMZ2_2	20030714	Product specification	-	PIMZ2_1
PIMZ2_1	20030602	Objective specification	-	-

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 17 November 2009

Document identifier: PIMZ2_PUMZ2_6